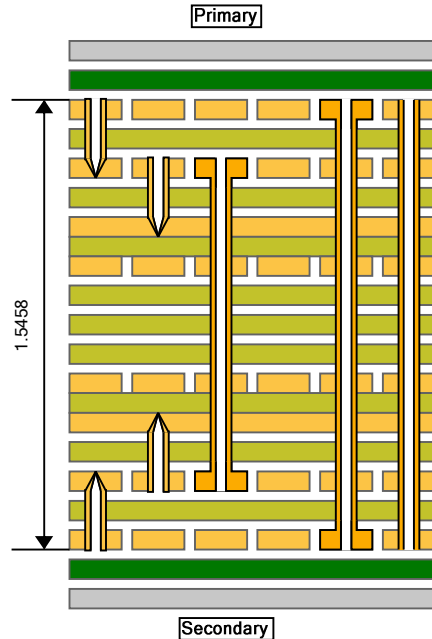


Layer	Stack up	Supplier Description	Description	Stock Number	Base Thickness	Finish Thickness	$\epsilon_r$	Impedance ID	N1
	<b>Primary</b>								
		ID/001	Screened Ident	600-001					
		SM/001	Liquid PhotoImageable Mask 1	500-001			4.000		
1		FO/001	Copper Foil	100-001	0.018	0.036	1, 2		
		PP/001	PrePreg 1080	300-001	0.076	0.076	4.200		
2		FO/001	Copper Foil	100-001	0.018	0.036	3		
		PP/001	PrePreg 1080	300-001	0.076	0.076	4.200		
3					0.036	0.036			
4		CO/020	FR4 Core	400-020	0.305	0.305	4.200		
					0.036	0.036	4, 5		
		PP/004	PrePreg 1651	300-004	0.152	0.152	4.200		
		PP/004	PrePreg 1651	300-004	0.152	0.152	4.200		
		PP/004	PrePreg 1651	300-004	0.152	0.152	4.200		
5					0.036	0.036			
6		CO/020	FR4 Core	400-020	0.305	0.305	4.200		
					0.036	0.036			
		PP/001	PrePreg 1080	300-001	0.076	0.076	4.200		
7		FO/001	Copper Foil	100-001	0.018	0.036			
		PP/001	PrePreg 1080	300-001	0.076	0.076	4.200		
8		FO/001	Copper Foil	100-001	0.018	0.036			
		SM/001	Liquid PhotoImageable Mask 1	500-001			4.000		
	<b>Secondary</b>	ID/001	Screened Ident	600-001					



Impedance ID	Structure Name
1	Coated Microstrip 1B
2	Edge Coupled Coated Microstrip 1B
3	Embedded Microstrip 1B1A
4	Offset Stripline 1B1A
5	Edge Coupled Offset Stripline 1B1A

StackName: Polar 8 HDI Mils Manufacture PCB	Version: A	Revision:	Modification:	Date of Revision:	Editor	Page 1/2
Date: 06/11/2007	Associated Documents:					
Author: JAS	Refer to Polar Specification Sheet POLAR-123.DOC for general Design requirements.					
Department: Engineering						
Site: Waterlooville						



**Notes**

PCB Thickness = 1.5 mm (+/- 10%)

- 1) Finished thicknesses (i.e. isolation distances) must be complied (within a +/- 15 % manufacturing tolerance) with to ensure consistent crosstalk characteristics and impedance.
- 2) Track and gap width may be modified to meet target impedances. This must be approved by engineering Dept. before PCB manufacture can commence.
- 3) If impedance targets cannot be met by modifying track geometries alone then dielectric thicknesses may be modified. This must be approved by engineering Dept. before PCB manufacture can commence.
- 4) To aid manufacturing via sizes may to modified and Cross-hatching may be added to outer layers, but must be placed a least 250 thou (6.35mm) away from any tracks, pads or board outline.
- 5) PCB must be tested to CAD net list supplied.
- 6) Min plating down barrels of holes 25um.
- 7) This PCB is to be supplied 2 up per panel. Scrap in panel acceptable.
- 8) Materials to be used must be UL-94V0, ROHS & WEEE compliant
- 9) ER (dk) of Material = 4.2

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Department: Engineering							
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